DATA SHEET

MPEG Multichannel

SAA2505H
Digital multi-channel audio IC (DUET)

Preliminary specification
File under Integrated Circuits, IC01

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Philips
Semiconductors

PHILIPS

Digital multi-channel audio IC (DUET) SAA2505H

FEATURES

Hardware features

- Two 40 MIPS 20-bit DSP cores
- All input and output buffer RAM is on-chip
- Program ROM on-chip for all decoding modes
- Two I²S-bus inputs with normal, double and quad speed mode (slave only)
- Second serial input usable for ADC (Karaoke input)
- Three normal and double speed I²S-bus outputs (slave and master from 256 and 384f_s)
- One normal, double, quad speed I²S-bus output (slave and master from 256 and 384f_s)
- Japanese EIAJ serial input and output formats
- Sony Philips Digital Interface (SPDIF) output
- I²C-bus control (up to 400 kHz)
- 3.3 V supply with 5 V TTL compatible inputs/outputs
- Boundary scan for printed-circuit board testing.

Software features

- AC-3 up to 5.1 channels
- MPEG 2 L2 up to 7.1 channels
- MPEG 1 L2 (Video-CD) 2 channels at 44.1 kHz
- Dolby pro-logic decoding at 32, 44.1 and 48 kHz
- Output configuration for 7, 5, 4, 3, 2 and 1 channels with or without Low Frequency Enhancement (LFE)
- Bass redirection for small satellite loudspeakers plus subwoofer
- Karaoke voice mix
- Dynamic range compression (AC-3 and MPEG)
- Adjustable delay up to 15 ms for surround channels (1.5 kbyte words)
- Adjustable delay up to 5 ms for centre channel (250 words)
- Rounding to DAC word length
- Mute by pin and I²C-bus command
- AC-3 and MPEG bitstream information available via the I²C-bus
- Concealment of CRC errors
- SPDIF coded output
- Fully programmable SPDIF channel status information.

APPLICATIONS

The SAA2505H is intended for all markets where a multi-channel audio decoder for Dolby AC-3 and MPEG 2 is required.

Primary markets are for DVD video players, TV sets and audio/video amplifiers.

GENERAL

The SAA2505H decodes multi-channel audio up to MPEG 7.1, AC-3 5.1 and pro-logic on a dual DSP core.

The device contains all of the RAM and ROM necessary for operation. This minimises the need for external components and no microcode download is required.

The device is primarily intended for audio/video surround sound amplifiers where the amplifier is connected to the data source by means of SPDIF (IEC 60958). The input interface is, therefore, made for SPDIF (IEC 60958) and formatted for the I²S-bus.

The primary device output is PCM, sent via four I²S-bus ports. There is also a SPDIF (IEC 60958) formatted output.

User control is achieved via an I²C-bus. However, the SAA2505H is capable of stand-alone operation.

MPEG Multichannel

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{DDD}	digital supply voltage		3.0	3.3	3.6	V
I_{DDD}	digital supply current		–	160	–	mA
V_{DDA}	analog supply voltage		3.0	3.3	3.6	V
I_{DDA}	analog supply current		–	tbf	–	mA
f_{xtal}	crystal frequency		–	35	–	MHz
T_{amb}	operating ambient temperature		0	–	70	°C
V_{ESD}	electrostatic discharge sensitivity for all pins	note 1	–2000	–	+2000	V
		note 2	–300	–	+300	V

Notes

1. Human body model: equivalent to discharging a 100 pF capacitor through a 1500 Ω resistor.
2. Machine model: equivalent to discharging a 200 pF capacitor through a 0 Ω resistor.

ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
SAA2505H	QFP64	plastic quad flat package; 64 leads (lead length 1.6 mm); body 14 × 14 × 2.7 mm	SOT393-1

BLOCK DIAGRAM

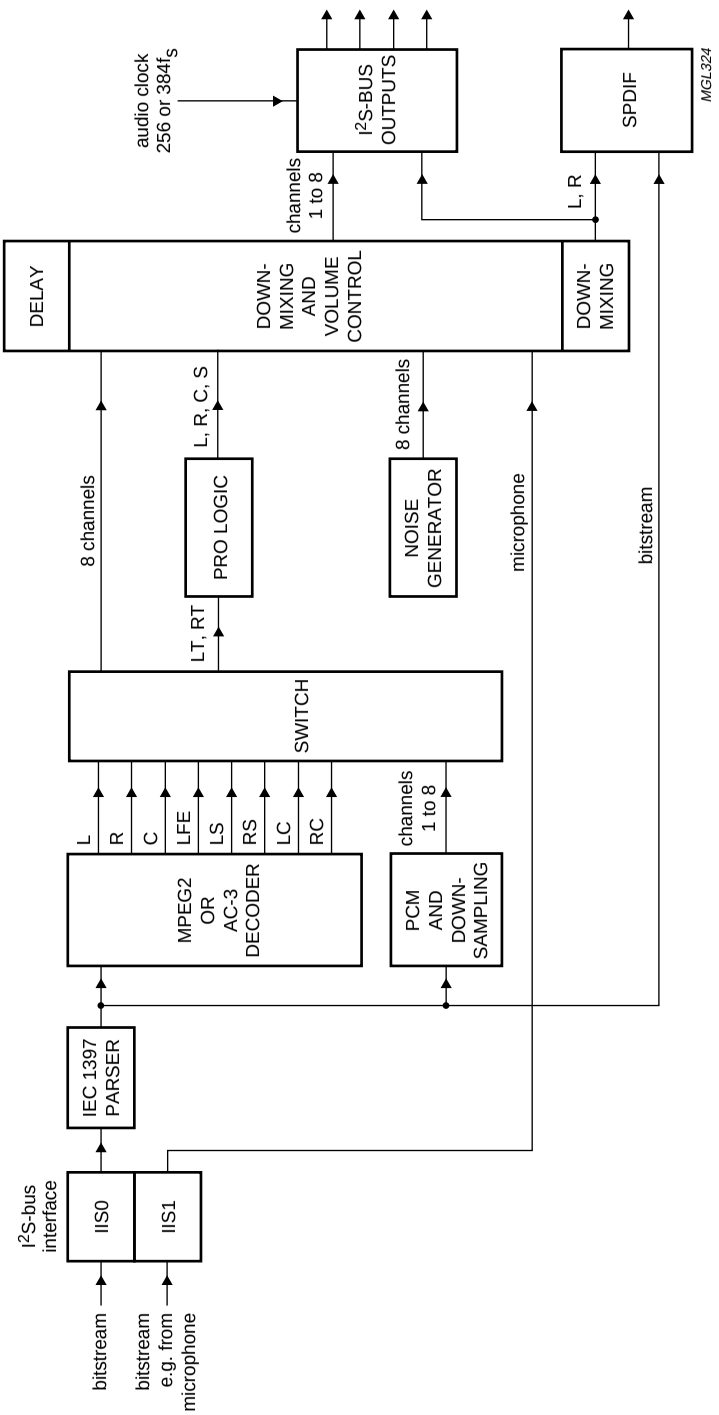


Fig.1 Simplified block diagram.

PINNING

SYMBOL	PIN	DRIVE/ LOAD[1]	TYPE	DESCRIPTION
STANDALONE	1	A	I	select stand-alone mode input
EFO1	2	F	O	output flag FO1; from DSP2
EFO2	3	F	O	output flag FO2; from DSP2
EFO3	4	F	O	output flag FO3; from DSP2
EFO4	5	F	O	output flag FO4; from DSP1
EFO5	6	F	O	output flag FO5; from DSP1
EFO6	7	F	O	output flag FO6; from DSP1
V_{SSDI}	8	–	S	digital ground for internal logic and memories; note 2
V_{DDDI}	9	–	S	digital supply voltage for internal logic and memories (+3.3 V); note 3
EFI1	10	A	I	input flag FI1; to DSP2
EFI2	11	A	I	input flag FI2; to DSP1
EFI3	12	A	I	input flag FI3; to DSP1
V_{DDDE}	13	–	S	digital supply voltage for I/O cells (+3.3 V); note 4
WSO	14	G	I/O	word select input/output for ports 0 to 2; also used for output port 3 when not in quad mode (I^2S-bus)
SCK	15	G	I/O	serial clock input/output for ports 0 to 2; also used for output port 3 when not in quad mode (I^2S-bus)
V_{SSDE}	16	–	S	digital ground for I/O cells; note 5
SDO0	17	F	O	serial data output for port 0 (I^2S-bus)
SDO1	18	F	O	serial data output for port 1 (I^2S-bus)
V_{DDDE}	19	–	S	digital supply voltage for I/O cells (+3.3 V); note 4
V_{SSDI}	20	–	S	digital ground for internal logic and memories; note 2
V_{DDDI}	21	–	S	digital supply voltage for internal logic and memories (+3.3 V); note 3
V_{SSDI}	22	–	S	digital ground for internal logic and memories; note 2
V_{DDDI}	23	–	S	digital supply voltage for internal logic and memories (+3.3 V); note 3
V_{DDDI}	24	–	S	digital supply voltage for internal logic and memories (+3.3 V); note 3
V_{SSDI}	25	–	S	digital ground for internal logic and memories; note 2
V_{DDDE}	26	–	S	digital supply voltage for I/O cells (+3.3 V); note 4
SDO2	27	F	O	serial data output for port 2 (I^2S-bus)
SDO3	28	F	O	serial data output for port 3 (I^2S-bus)
V_{SSDE}	29	–	S	digital ground for I/O cells; note 5
WSO3	30	F	O	word select output for port 3; used in quad mode (I^2S-bus)
SCKO3	31	F	O	serial clock output for port 3; used in quad mode (I^2S-bus)
V_{DDDE}	32	–	S	digital supply voltage for I/O cells (+3.3 V); note 4
SDB	33	F	O	serial data begin output for port 3; used in quad mode (I^2S-bus)
SPDIF	34	F	O	SPDIF output
V_{SSDE}	35	–	S	digital ground for I/O cells; note 5
V_{SSDI}	36	–	S	digital ground for internal logic and memories; note 2
V_{DDDI}	37	–	S	digital supply voltage for internal logic and memories (+3.3 V); note 3

SYMBOL	PIN	DRIVE/ LOAD[1]	TYPE	DESCRIPTION
V_{SSDE}	38	–	S	digital ground for I/O cells; note 5
SYSCLK	39	E	O	programmable system clock output
V_{DDDE}	40	–	S	digital supply voltage for I/O cells (+3.3 V); note 4
V_{DDA}	41	–	S	analog supply voltage for crystal oscillator (+3.3 V)
CLKI	42	H	I	oscillator input
CLKO	43	H	O	oscillator output
V_{SSDA}	44	–	S	digital ground for crystal oscillator
ACLK	45	A	I	audio clock input for master mode
V_{SSDE}	46	–	S	digital ground for I/O cells; note 5
TDI	47	B	I	boundary scan test data input (this pin should be pulled HIGH for normal operation)
TMS	48	B	I	boundary scan test mode select input (this pin should be pulled HIGH for normal operation)
TCK	49	B	I	boundary scan test clock input
$\overline{TRST}$	50	B	I	boundary scan test reset input (this pin should be pulled LOW for normal operation)
TDO	51	B	O	boundary scan test data output
V_{DDDI}	52	–	S	digital supply voltage for internal logic and memories (+3.3 V); note 3
V_{SSDI}	53	–	S	digital ground for internal logic and memories; note 2
WSI	54	A	I	word select input for ports 0 and 1 (I^2S-bus)
SDBI	55	A	I	serial data begin input for port 0 (I^2S-bus)
SDI0	56	A	I	serial data input for port 0 (I^2S-bus)
SDI1	57	A	I	serial data input for port 1 (I^2S-bus)
SCKI	58	A	I	serial clock input for ports 0 and 1 (I^2S-bus)
V_{SSDI}	59	–	S	digital ground for internal logic and memories; note 2
V_{DDDI}	60	–	S	digital supply voltage for internal logic and memories (+3.3 V); note 3
RESET	61	C	I	hardware reset
ADDR	62	A	I	select address input (I^2C-bus)
SCL	63	C	I	serial clock input; external pull-up to +5 V (I^2C-bus)
SDA	64	D	I/O	serial data input/output; external pull-up to +5 V (I^2C-bus)

Notes

1. See Table 1.
2. All V_{SSDI} pins are internally connected.
3. All V_{DDDI} pins are internally connected.
4. All V_{DDDE} pins are internally connected.
5. All V_{SSDE} pins are internally connected.

Table 1 Pin drive and load descriptions

DRIVE/LOAD	DESCRIPTION
A	+5 V tolerant input; TTL characterized with internal pull-down resistor
B	+5 V tolerant input; TTL characterized with internal pull-up resistor
C	+5 V tolerant input; TTL Schmitt-trigger characterized
D	+5 V tolerant 400 kHz (I^2C-bus)
E	TTL characterised +5 V tolerant 3-state output with 3 mA drive capability
F	TTL characterised +5 V tolerant 3-state slew rate limited output with 3 mA drive capability
G	+5 V tolerant bidirectional 3-state pin; with 3 mA output drive and slew rate limiting; TTL level input; without pull-up or pull-down resistor
H	crystal pins

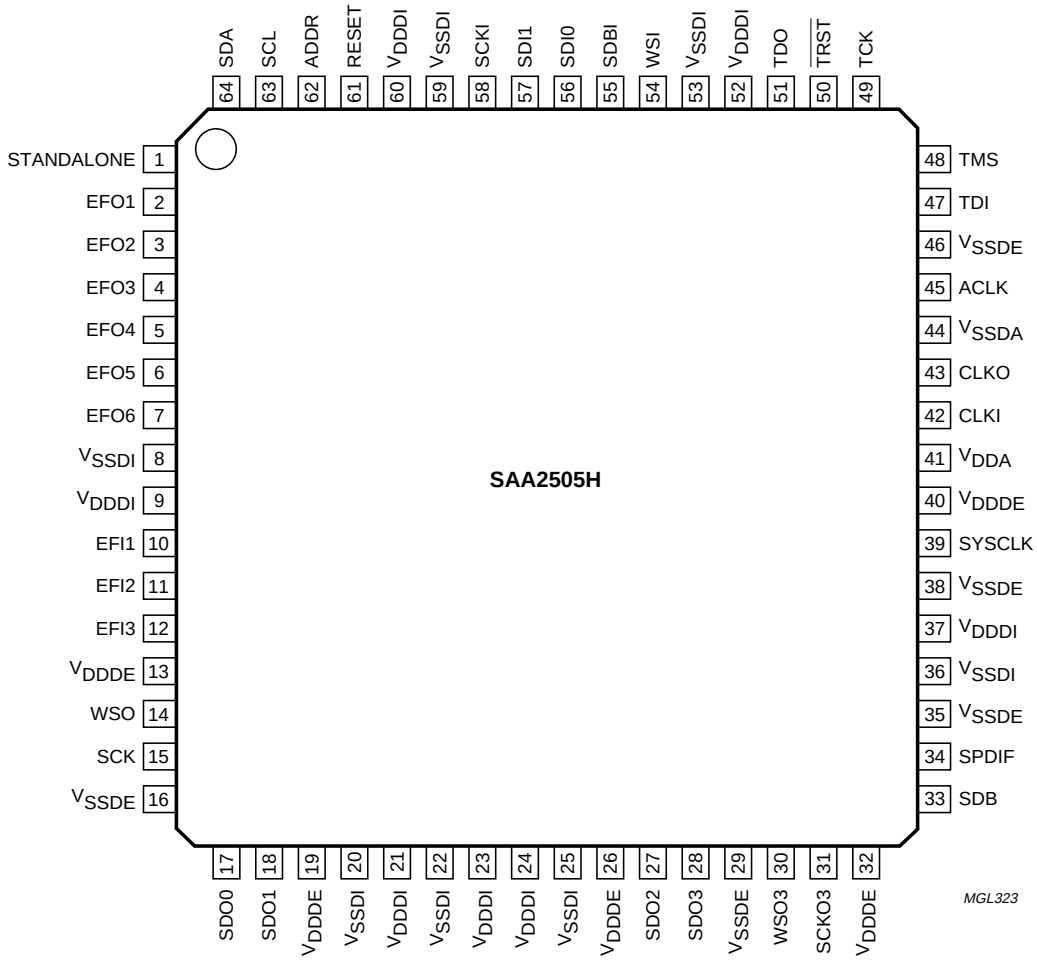


Fig.2 Pin configuration.

CLOCK BUILD-UP

Up to four clocks provide the timing information for the SAA2505H. These are as follows:

1. Data source clock
2. Data processing clock
3. I²C-bus data/control clock
4. Data sink clock.

Data source clock

Clocking of the input data is derived from the serial clock input at pin 58 and is compliant with the I²S-bus and EIAJ transfer formats. The ports are capable of operating at normal, double and quad speed.

Data processing clock

This clock is used for data processing and internal data transfer. The clock can either be provided by an external clock generator having a duty cycle between 40 and 60% or by using the internal crystal clock generator and an external crystal. The external clock should be connected between pins 42 (CLKI) and 43 (CLKO) (see Fig.11).

To use the internal clock a 35 MHz crystal operating on the 3rd harmonic must be connected between pins 42 and 43 (CLKI and CLKO).

A buffered version of this clock is available at pin 39 (SYSCLK). This can be optionally disabled or, a divided version (4, 2 and 1) of the clock input at pin 42 (CLKI) can be made available.

I²C-bus data/control clock

The I²C-bus control logic supports I²C-bus clock speeds up to 400 kHz. This is supplied to pin 63 (SCL). If the SAA2505H is in the stand-alone mode (pin 1 HIGH) no I²C-bus clock needs to be supplied.

Data sink clock

The data sink clock source is dependant on the mode of operation of the I²S-bus output ports.

In the master mode the I²S-bus clock is derived form an external 256 or 384f_s source connected to pin 45 (ACLK). This is internally divided and used to drive the serial clock at pins 15 and 31 (SCK and SCKO3). To ensure that the digital outputs poses good timing qualities (jitter and wander) pin 45 should be a connected to a high quality timing source.

In the I²S-bus slave mode the output data is clocked to pin 15. This can either be the serial clock input at pin 58 (SCKI) or a suitable external clock. When in slave mode the signal at pin 15 is replicated at pin 31.

FUNCTIONAL DESCRIPTION

Data sinks

Coded audio data or PCM audio data can be input to both DSPs from two slave-only serial interfaces capable of receiving data in either I²S-bus or EIAJ formats. Both serial interfaces use the same serial clock (pin 58) and word select input (pin 54). The serial clock must be at least 32f_s.

Serial data is applied to pins 56 and 57 (SDI0 and SDI1). These pins are mode shared between the I²S-bus and EIAJ formatted serial data. Port mode selection is achieved via the I²C-bus interface, see Table 3.

I²S-BUS FORMATTED SPDIF INFORMATION

In the I²S-bus mode ‘big-endian’ data is received, MSB justified to 1 clock period after a falling edge of the word select output. The data stream should be formatted according to *“IEC 60958 - SPDIF”* including the extensions for non-PCM encoded audio data (“*IEC 61937*”).

AC-3 and MPEG coded data is formatted in 16-bit words. These words are expected at a sample rate (f_s) of 48 kHz and thus a minimum serial clock of 1.536 MHz; two 16-bit words per word select period. If the transmission word length is in excess of 16 bits all additional bits are discarded.

PCM sample lengths of up to 20-bit words are supported with sample rates of 44.1 and 48 kHz. This mode is used to transfer PCM and PCM with Dolby pro-logic encoded data. Word select LOW corresponds to transmission of data for the left channel, word select HIGH corresponds to transmission of data for the right channel.

Pin 55 (SDBI) is reserved for a multi-channel extension to the I²S-bus and is currently not supported.

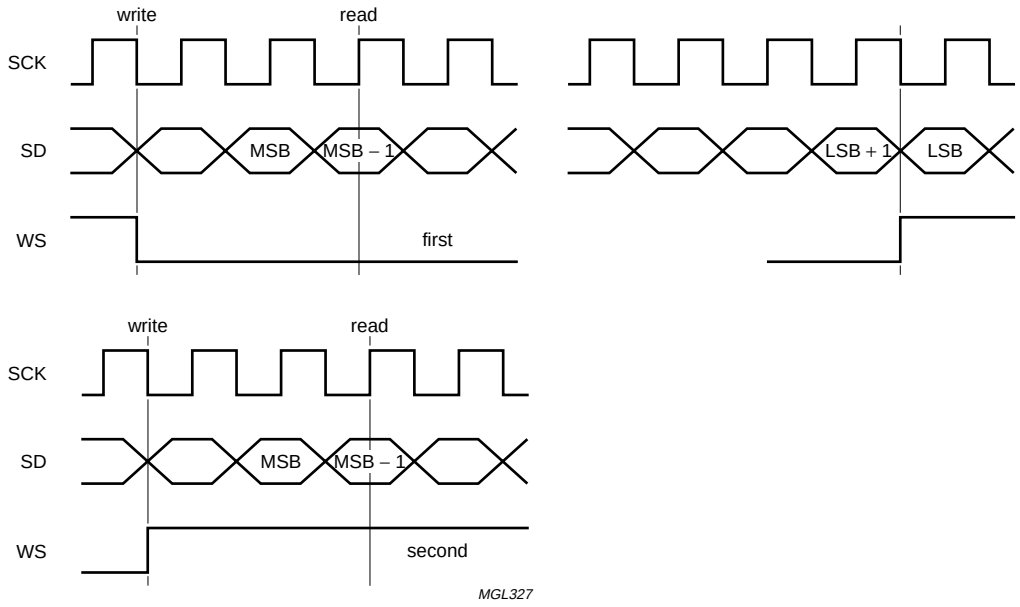


Fig.3 I^2S-bus format (MSB fixed).

EIAJ FORMATTED INPUTS

In EIAJ mode ‘big-endian’ data is received LSB justified to the rising edge of word select output. Formatting of the data is identical to that used in the I^2S-bus mode.

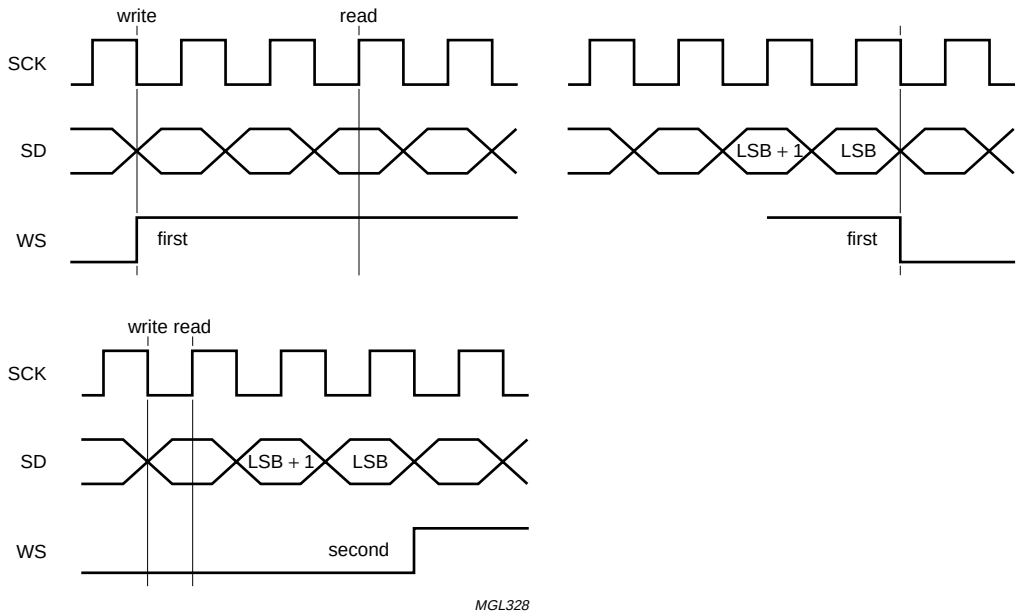


Fig.4 EIAJ format (LSB justified).

Data sources

I²S-BUS AND EIAJ FORMATTED OUTPUTS

The device has four I²S-bus/EIAJ mode select outputs. These outputs are capable of outputting data in EIAJ 20, 18 or 16-bit and I²S-bus modes. The EIAJ outputs are capable of operating in single or double speed, the I²S-bus output is capable of operating in single, double and quad speed.

The output ports can either be in the slave or master mode. In the slave mode they can either be slaved to the I²S-bus serial clock input (pin 15) or to an external clock. In the master mode an audio clock is applied to pin 45 that is 256 or 384f_s. The master clocking scheme allows the support of a 96 kHz sample rate DAC by use of the double speed output option. The quad speed output option is intended to allow multiple SAA2505H devices to be connected together.

In order to obtain a high quality digital output in the master mode the audio clock should be of high quality, having low jitter and an even mark space ration.

SPDIF FORMATTED OUTPUT

The SPDIF output can transmit either coded data, as received from the serial data input at pin 56 (SDI0), or down-mixed 20-bit PCM stereo. The down-mixed stereo may be Pro-logic encoded.

Together with the PCM samples additional control bits are transmitted. These are the channel status, user data and validity bits.

The first five bytes of the channel status bits are user programmable, all following bytes are zeroed automatically. Transmission is LSB first.

The user data can carry message lengths of 129 bytes. These are transmitted over the SPDIF port at a rate of 2 bits per stereo sample. The message buffer of 129 bytes is loaded via the I²C-bus, if no message is written the SAA2505H outputs all zeros for the user data.

Table 2 Output port timing information

MODE	AUDIO CLOCK SAMPLING FREQUENCY	WORD SELECT SAMPLING FREQUENCY	SERIAL CLOCK SAMPLING FREQUENCY	SERIAL DATA BEGIN SAMPLING FREQUENCY
Single	256 or 384f_s	1f_s	64f_s	–
Double	256 or 384f_s	2f_s	128f_s	–
Quad	256f_s	4f_s	256f_s	1f_s
Quad	384f_s	4f_s	192f_s	1f_s

Control Inputs

The SAA2505H can be operated in two stand-alone modes or can be managed by the I²C-bus.

STAND-ALONE MODES

Two stand-alone modes exist to allow the device to be used in systems without a microcontroller. These two modes are STANDALONE (pin 1) held HIGH and STANDALONE connected to RESET (pin 61).

When pin 1 is LOW a reset defaults the outputs to quiet, however when pin 1 is HIGH a reset defaults the I²S-bus output to active and the SPDIF output to mute. When pin 1 is HIGH some of the I²C-bus registers cannot be accessed see Table 3.

I²C-BUS REGISTER CONTROL

The I²C-bus port supports 5 V, 400 kHz operation. The details of the registers are given in Table 3.

Table 3 I^2C-bus control register

SECTION	REGISTER NAME	MEMORY ADDRESS	DEFAULT VALUE			DESCRIPTION
			1(1)	**2**(2)	**3**(3)	
General	SOFT_RESET	$8 000-b0	0	0	0	0: operation
						1: reset
General	SYSCLCKEN	$8 000-b1	0	note 4	1	0: enable SYSCLK output
						1: disable SYSCLK output
General	SYSCLKDIV	$8 000-b3 and b2	00	note 4	10	00: SYSCLK = $\frac{1}{4}$CLK
						01: SYSCLK = $\frac{1}{2}$CLK
						10: SYSCLK = CLK
						11: reserved
General	EN_INP_INT_DSP1	$8 000-b4	0	note 4	1	0: disable input interrupts on DSP1
						1: enable input interrupts on DSP1
General	EN_OUTP_INT_DSP1	$8 000-b5	0	note 4	0	0: disable output interrupts on DSP1
						1: enable output interrupts on DSP1
General	EN_INP_INT_DSP1	$8 000-b6	0	note 4	1	0: disable input interrupts on DSP2
						1: enable input interrupts on DSP2
General	EN_OUTP_INT_DSP1	$8 000-b7	0	note 4	0	0: disable output interrupts on DSP2
						1: enable output interrupts on DSP2
General	ACLKSEL	$8 000-b8	0	note 4	0	0: ACLK = $256f_s$
						1: ACLK = $384f_s$
General	MEMCONFIG	$8 000-b9	0	note 4	0	0: program memory on DSP1 = 12 kbytes
						0: program memory on DSP2 = 8 kbytes
						1: program memory on DSP1 = 8 kbytes
						1: program memory on DSP2 = 12 kbytes
I^2SCONTROL	IISMODE	$8 001-b1 and b0	00	note 4	00	00: I^2S-bus/EIAJ input format
						01: reserved
						10: reserved
						11: reserved
I^2SCONTROL	IISINP	$8 001-b2	0	note 4	0	0: I^2S-bus input format
						1: EIAJ 16-bit input format
I^2SCONTROL	IISI_SDB_EN	$8 001-b3	0	note 4	0	0: SDBI is DSP1 Input flag
						1: SDBI is aligned to WS to allow multi-channel I^2S-bus input

SECTION	REGISTER NAME	MEMORY ADDRESS	DEFAULT VALUE			DESCRIPTION
			1[1]	2[2]	3[3]	
I²SCONTROL	reserved	$8 001-b4	0	note 4	0	reserved
I²SCONTROL	IISOUTMOD	$8 001-b6 and b5	00	note 4	00	00: I²S-bus format data output
						01: EIAJ 16-bit format data output
						10: EIAJ 18-bit format data output
						11: EIAJ 20-bit format data output
I²SCONTROL	IISOUTMST	$8 001-b7	0	note 4	0	0: I²S-bus outputs are slaves
						1: I²S-bus outputs are masters
I²SCONTROL	IISOUTSPD	$8 001-b8	0	note 4	0	0: I²S-bus outputs 0 to 2 operate at normal speed
						1: I²S-bus outputs 0 to 2 operate at double speed
I²SCONTROL	IIS3OUTSPD	$8 001-b10 and b9	00	note 4	00	00: I²S-bus output 3 operates at normal speed
						01: I²S-bus output 3 operates at double speed
						10: I²S-bus output 3 operates at quad speed
						11: I²S-bus output 3 operates at normal speed
I²SCONTROL	IISO0EN	$8 001-b11	0	note 4	1	0: SDO0 output 3-stated
						1: SDO0 output enabled
I²SCONTROL	IISO1EN	$8 001-b12	0	note 4	1	0: SDO1 output 3-stated
						1: SDO1 output enabled
I²SCONTROL	IISO2EN	$8 001-b13	0	note 4	1	0: SDO2 output 3-stated
						1: SDO2 output enabled
I²SCONTROL	IISO3EN	$8 001-b14	0	note 4	1	0: SDO3 output 3-stated
						1: SDO3 output enabled
I²SCONTROL	IIS3CLKEN	$8 001-b15	0	note 4	0	0: SCKO3, WSO3 and SDB outputs 3-stated
						1: SCKO3, WSO3 and SDB outputs enabled
SPDIF1	SPDIFVAL	$8 002-b0	0	0	0	0: SPDIF validity bit = 0
						1: SPDIF transmitting valid PCM
SPDIF1	SPDIFBYP	$8 002-b1	0	0	0	0: output PCM data from DSP1
						1: output I²S-bus data from I²S-bus input
SPDIF1	IISUBIT	$8 002-b2	0	0	0	reserved
SPDIF1	SPDIFEN	$8 002-b3	0	0	0	0: 3-state SPDIF output and reset SPDIF block
						1: enable SPDIF output

SECTION	REGISTER NAME	MEMORY ADDRESS	DEFAULT VALUE			DESCRIPTION
			1(1)	2(2)	3(3)	
Normal usage						
SPDIF1	CSBYTE0	$8 002-b15 to b8	0000 0000			b8: consumer mode
						b9: LPCM
						b10: copy protection
						b11 to b13: pre-emphasis
						b14 to b15: mode
SPDIF2	CSBYTE1	$8 003-b7 to b0	0000 0000			b0 to b7: category code
SPDIF2	CSBYTE2	$8 003-b15 to b8	0000 0000			b8 to b11: source
						b12 to b15: channel number
SPDIF3	CSBYTE3	$8 003-b7 to b0	0000 0000			b0 to b3: source
						b4 to b6: clock accuracy
SPDIF3	CSBYTE4	$8 003-b15 to b8	0000 0000			b0 to b3: word length

Notes

1. STANDALONE held LOW.
2. STANDALONE held HIGH.
3. STANDALONE connected to RESET.
4. Controlled by DSP; no I^2C-bus access.

All unused bits return a value of 0.

I²C-bus control and commands (pins 63 and 64)

INTRODUCTION

A general description of *"The I²C-bus and how to use it"* can be obtained from Philips sales offices using ordering number 9398 393 40011.

For the external control of the SAA2505H a fast I²C-bus is implemented. This is a 400 kHz bus which is downward compatible with the standard 100 kHz bus. There are two different types of control instructions:

- Instructions to control the DSP program; programming the coefficient RAM and reading the values of parameters
- Instructions controlling source selection and programmable parts; through the control registers as detailed in Table 3.

The detailed description of the I²C-bus and commands is given in the following sections.

CHARACTERISTICS OF THE I²C-BUS

The I²C-bus is for 2-way, 2-line communication between different ICs or modules. The two lines are the serial data line (SDA) and the serial clock line (SCL). Both lines must be connected to the supply rail via a pull-up resistor when connected to the output stages of a microcontroller. For a 400 kHz I²C-bus, the recommendation from Philips Semiconductors must be followed (e.g. up to loads of 200 pF on the bus a pull-up resistor can be used, between 200 and 400 pF a current source or switched resistor must be used). Data transfer can only be initiated when the bus is not busy.

BIT TRANSFER

One data bit is transferred during each clock pulse.
The data on the SDA line must remain stable during the HIGH period of the clock pulse as changes in the data line at this time will be interpreted as control signals.
The maximum clock frequency is 400 kHz. To be able to run at this high frequency all of the Inputs and outputs connected to the bus must be designed for this high speed I²C-bus according the Philips specification (see Fig.5).

START AND STOP CONDITIONS

Both data and clock line will remain HIGH when the bus in not busy. A HIGH-to-LOW transition of the data line while the clock is HIGH is defined as a STOP condition (P) (see Fig.6).

A LOW-to-HIGH transition of the data line while the clock is HIGH is defined as a START condition (S) (see Fig.6).

DATA TRANSFER

A device generating a message is a 'transmitter', a device receiving a message is the 'receiver'. The device that controls the message is the 'master' and the devices which are controlled by the master are the 'slaves' (see Fig.7).

ACKNOWLEDGE

The number of data bits transferred between the START and STOP conditions from the transmitter to the receiver is not limited. Each byte of 8 bits is followed by one acknowledge bit. The acknowledge bit is a HIGH level left on the bus by the transmitter whereas the master generates an extra acknowledge related clock pulse.
A slave receiver which is addressed must generate an acknowledge after the reception of each byte. Also a master must generate an acknowledge after the reception of each byte that has been clocked out of the slave transmitter. The device that acknowledges has to pull-down the SDA line, left HIGH by the transmitter, during the acknowledge clock pulse, so that the SDA line is stable LOW during the HIGH period of the acknowledge related clock pulse. Set-up and hold times must be taken into account. A master receiver must signal an end-of-data to the transmitter by not generating an acknowledge on the last byte that has been clocked out of the slave. In this event the transmitter must leave the data line HIGH to enable the master to generate a STOP condition (see Fig.8).

STATE OF THE I²C-BUS INTERFACE DURING AND AFTER POWER-ON RESET

During power-on reset the internal SDA line is kept HIGH and the SDA pin is therefore high impedance. The SDA line remains HIGH until a master pulls it down to initiate communication.

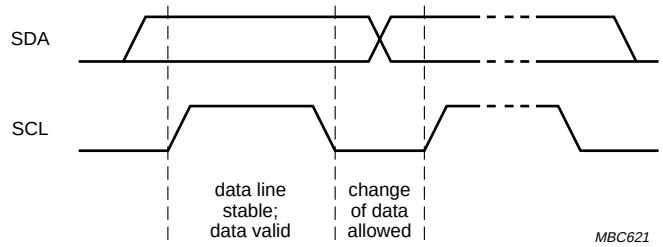


Fig.5 Bit transfer on the I^2C-bus.

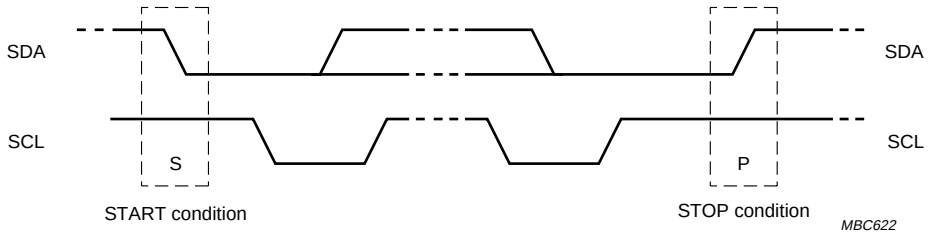


Fig.6 START and STOP conditions.

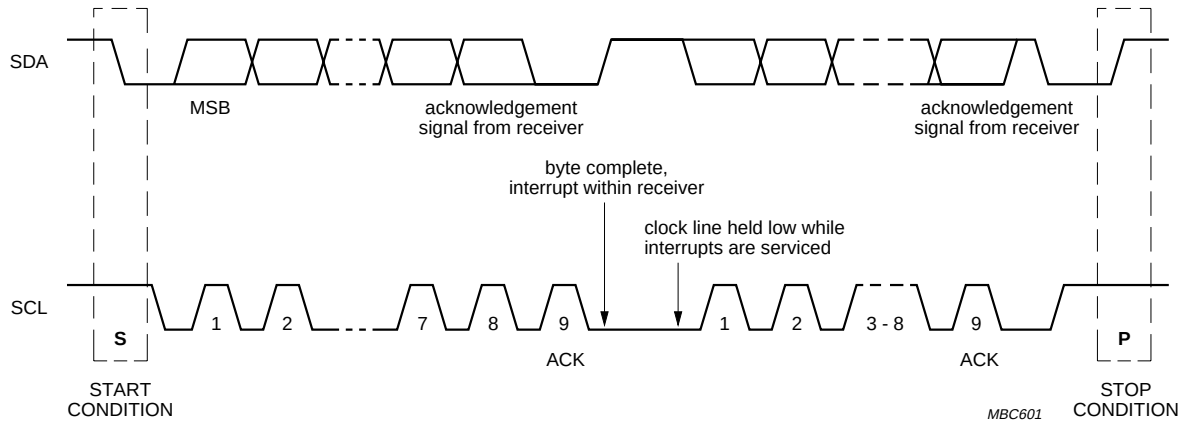


Fig.7 Data transfer on the I²C-bus.

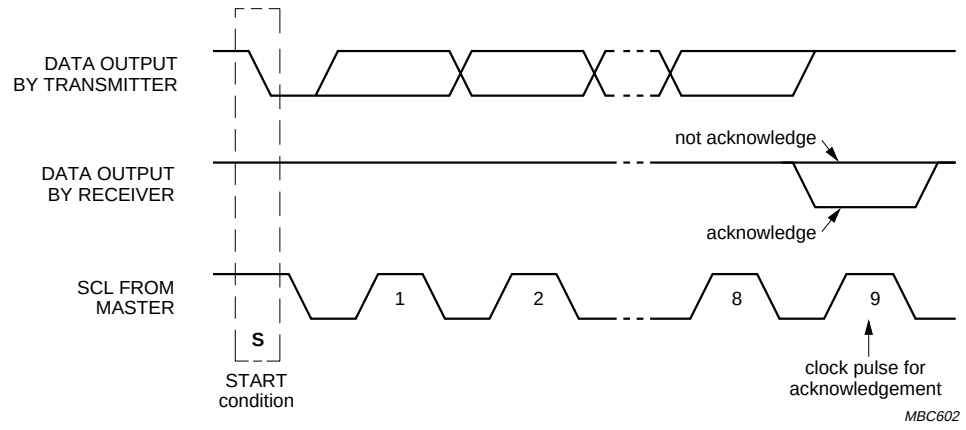


Fig.8 Acknowledge on the I²C-bus.

I²C-bus format

ADDRESSING

Before any data is transmitted on the I²C-bus, the device which should respond is addressed first. The addressing is always done with the first byte transmitted after the start procedure.

SLAVE ADDRESS SELECTION (PIN 62)

The SAA2505H acts as slave receiver or a slave transmitter. Therefore the clock signal (SCL) is only an input signal. The data signal (SDA) is a bidirectional line. The SAA2505H slave addresses are shown in Table 4.

Table 4 I²C-bus address

I²C-BUS LEVEL	I²C-BUS ADDRESS
1	59H
0	58H

The subaddress bit A0 corresponds to the hardware address at pin 52 which allows the device to have 2 different addresses. This allows control of two DUET ICs via the same I²C-bus.

WRITE AND READ CYCLES

The I²C-bus configuration for a write cycle is shown in Table 5. The write cycle is used to write the bytes to memory and control registers.

The I²C-bus configuration for a read cycle is shown in Table 6. The read cycle is used to read bytes from memory and control registers.

Table 5 I²C-bus write sequence

I²C-BUS MASTER	SAA2505H
START	–
I²C-bus address of SAA2505H	–
Write	–
–	acknowledge
Address high part	–
–	acknowledge
Address low part	–
–	acknowledge
Data high part	–
–	acknowledge
Data medium part	–
–	acknowledge
Data low part	–
–	acknowledge
Data high part	–
–	acknowledge
Data medium part	–
–	acknowledge
Data low part	–
–	acknowledge
Continued exchanges	
STOP Condition	–

Table 6 I²C-bus read sequence

I²C-BUS MASTER	SAA2505H
START	–
I²C-bus address of SAA2505H	–
Write	–
–	acknowledge
Address high part	–
–	acknowledge
Address low part	–
–	acknowledge
START	–
I²C-bus address of SAA2505H	–
Read	–
–	acknowledge
–	data high part
–	acknowledge
–	data medium part
–	acknowledge
–	data low part
–	acknowledge
–	data high part
–	acknowledge
–	data medium part
–	acknowledge
–	data low part
–	acknowledge
Continued Exchanges	
STOP Condition	–

All RAM and peripheral registers are mapped into a common 16-bit address range. The data words are all MSB padded to 24-bit, however, the on-chip RAM is 20-bit and therefore the 4 MSBs are padded with zeros.

Table 7 SAA2505H I²C-bus address ranges

START	STOP	MEMORY BLOCK
$0	$1FFF	DSP1 X memory
$2000	$3FFF	DSP1 Y memory
$4000	$5FFF	DSP2 X memory
$6000	$7FFF	DSP2 Y memory
$8000	$9FFF	control registers

Power supply connections and EMC

The digital part of the chip has in total 13 positive supply line connections and 13 ground connections. To minimise radiation the device should be put on a double layer PCB with, on one side, a large ground plane. The ground supply lines should have a short connection to this ground plane. The supply line connections should have minimum inter-pin PCB track impedances. A low reactance (Q) ferrite bead/capacitor network in the positive supply line can be used as a high frequency filter. Special attention should be paid to the analog supply lines (V_{DDA} and V_{SSA}).

Boundary scan test interface

The SAA2505H has a 5 pin boundary scan test interface which implements the three required commands of the IEEE1149; BYPASS, SAMPLE and EXTEST.

The boundary scan test interface uses the following pins TDI (pin 47), TMS (pin 48), TCK (pin 49), $\overline{\text{TRST}}$ (pin 50) and TDO (pin 51). Naming and use of the pins is as per IEEE recommendations.

Though $\overline{\text{TRST}}$, TMS and TDI have internal pull-up resistors there should also be system level pull-up resistors.

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{DDD}	digital supply voltage		–0.3	+3.3	V
ΔV_{DDD}	voltage difference between two supply voltage pins		–	330	mV
I_{IK}	DC input clamp diode current	$V_I < -0.3$ V or $V_I > V_{DDD} + 0.3$ V	–	±10	mA
I_{OK}	DC output clamp diode current	output type 4 mA; $V_O < -0.3$ V or $V_O > V_{DDD} + 0.3$ V	–	±10	mA
I_O	DC output source or sink current	output type 4 mA; -0.3 V $< V_O < V_{DDD} + 0.3$ V	–	±10	mA
I_{DDD} I_{SSD}	DC current per supply pin (V_{DDD} or V_{SSD})		–	±500	mA
T_{amb}	operating ambient temperature		0	70	°C
T_{stg}	storage temperature range		–55	+125	°C
LTCH	latch-up protection	CIC specification/test method	100	–	mA
V_{ESD}	electrostatic discharge sensitivity for all pins	note 1	–2000	+2000	V
		note 2	–300	+300	V

Notes

1. Human body model: equivalent to discharging a 100 pF capacitor through a 1500 Ω resistor.
2. Machine model: equivalent to discharging a 200 pF capacitor through a 0 Ω resistor.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
$R_{th(j-a)}$	thermal resistance from junction to ambient in free air	45	K/W

CHARACTERISTICS

Digital I/O at T_{amb} = 0 to 70 °C; V_{DDD} = 3.0 to 3.6 V; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{DDD}	digital supply voltage		3	3.3	3.6	V
V_{DDA}	analog supply voltage for the crystal oscillator		3	3.3	3.6	V
I_{DDD}	digital supply current	f_{xtal} = 41 MHz; maximum activity of the DSP	–	tbf	tbf	mA
$I_{DD(xtal)}$	supply current for the crystal oscillator	f_{xtal} = 41 MHz; functional mode	–	tbf	tbf	mA
P_{tot}	total power dissipation	f_{xtal} = 41 MHz; maximum activity of the DSP	–	tbf	tbf	W
V_{hys}	schmitt trigger hysteresis	pin type SCHMITCD	0.4	–	0.7	V
V_{IH}	HIGH-level input voltage	$I_o = -3$ mA; pin types A, B and C	2.0	–	–	V
V_{IL}	LOW-level input voltage	V_{DDD} = 3.0 V; I_o = 3 mA; pin types A, B and C	–	–	0.8	V

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{OH}	HIGH-level digital output voltage	I_o = –3 mA; pin types A, B and C	2.4	–	–	V
V_{OL}	LOW-level digital output voltage	V_{DDD} = 3.0 V; I_o = 3 mA; pin types A, B and C	–	–	0.4	V
$V_{OL(I2C)}$	LOW-level digital output voltage and I^2C-bus data output	I_o = 8 mA; pin type D	–	–	0.4	V
$I_{LO(Z)}$	output leakage current, 3-state outputs	V_o = 0 or V_{DDD}; pin types A, B and C	–	–	±5	μA
$R_{pu(int)}$	internal pull-up resistor to V_{DDDX}	pin type B	–	76	–	kΩ
$R_{pd(int)}$	internal pull-down resistor to V_{SSDX}	pin type A	–	76	–	kΩ
$t_{i(r)}$	input rise time	V_{DDD} = 3.6 V	–	tbf	3.6	ns
$t_{i(f)}$	input fall time	V_{DDD} = 3.6 V	–	tbf	3.6	ns
$t_{o(r)}$	output rise time	pin types E, F and G; V_{DDD} = 3.3 V; T_{amb} = 25 °C; process = 0 σ; C_L = 20 pF	–	–	3.0	ns
$t_{o(f)}$	output fall time	pin types E, F and G; V_{DDD} = 3.3 V; T_{amb} = 25 °C; process = 0 σ; C_L = 20 pF	–	–	3.5	ns
Oscillator input/output						
f_{xtal}	crystal frequency		40	40.5	–	MHz
V_{xtal}	voltage across the crystal		3.0	3.3	3.6	V
g_m	transconductance	at start-up	10.5	19	32	mS
		in operating range	3.6	–	38	mS
$C_{L(CLK)}$	capacitive load of clock output		–	500	1000	fF
$T_{cy(STRTU)}$	number of cycles in start-up time	depends on quality of the external crystal	–	1000	–	cycles

TIMING CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Serial digital inputs and outputs; (see Fig.9)					
t_r	rise time	T_{cy} = 50 ns	–	7.5	ns
t_f	fall time	T_{cy} = 50 ns	–	7.5	ns
T_{cy}	bit clock cycle time		70	–	ns
$t_{BCK(H)}$	bit clock time HIGH	T_{cy} = 50 ns	17.5	–	ns
$t_{BCK(L)}$	bit clock time LOW	T_{cy} = 50 ns	17.5	–	ns
$t_{s;DAT}$	data set-up time host	T_{cy} = 50 ns	320	–	ns
$t_{s;DAT}$	data set-up time I^2S-bus input		10	–	ns
$t_{h;DAT}$	data hold time host	T_{cy} = 50 ns	50	–	ns
$t_{h;DAT}$	data hold time I^2S-bus input		10	–	ns
$t_{s;WS}$	word select set-up time I^2S-bus input	T_{cy} = 50 ns	100	–	ns
$t_{h;WS}$	word select hold time I^2S-bus input	T_{cy} = 50 ns	100	–	ns
$t_{d;DAT}$	data delay time host		–	20	ns
$t_{d;WS}$	word select delay time host		–	15	ns
I^2C-bus timing; (see Fig.10)					
f_{SCL}	SCL clock frequency		0	400	kHz
t_{BUF}	bus free between a STOP and START condition		1.3	–	µs
$t_{HD;STA}$	hold time (repeated) start condition; after this period the first clock pulse is generated		0.6	–	µs
t_{LOW}	LOW period of the SCL clock		1.3	–	µs
t_{HIGH}	HIGH period of the SCL clock		0.6	–	µs
$t_{SU;STA}$	set-up time for a repeated start condition		0.6	–	µs
$t_{HD;DAT}$	data hold time		0	0.9	µs
$t_{SU;DAT}$	data set-up time	for standard mode I^2C-bus system $t_{SU;DAT}$ > 250 ns	100	–	ns
t_r	rise time of both SDA and SCL signals	f_{SCL} = 400 kHz	$20 + 0.1C_{bus}$(1)	300	ns
		f_{SCL} = 100 kHz	$20 + 0.1C_{bus}$(1)	1000	ns
t_f	fall time of both SDA and SCL signals		$20 + 0.1C_{bus}$(1)	300	ns
$t_{SU;STO}$	set-up time for STOP condition		0.6	–	µs
$C_{L(bus)}$	capacitive load for each bus line		–	400	pF
t_{SP}	pulse width of spikes which must be suppressed by the input filter	f_{SCL} = 400 kHz	0	50	ns

Note

1. C_{bus} = bus line capacitance in pF.

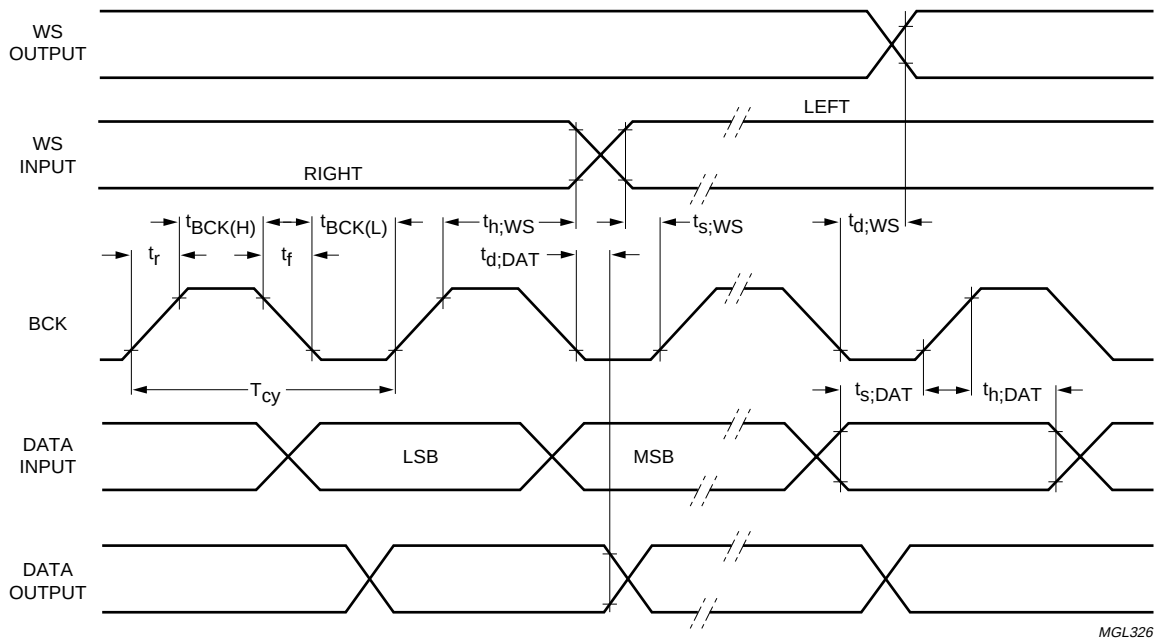


Fig.9 Timing definitions of the serial digital data inputs and outputs.

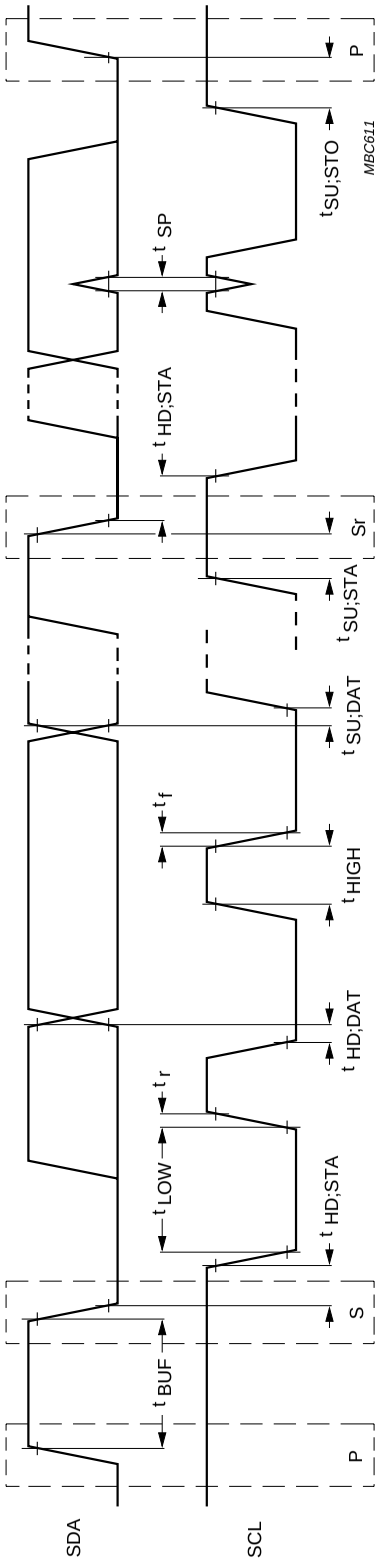


Fig.10 Timing definition of the I²C-bus.

APPLICATION INFORMATION

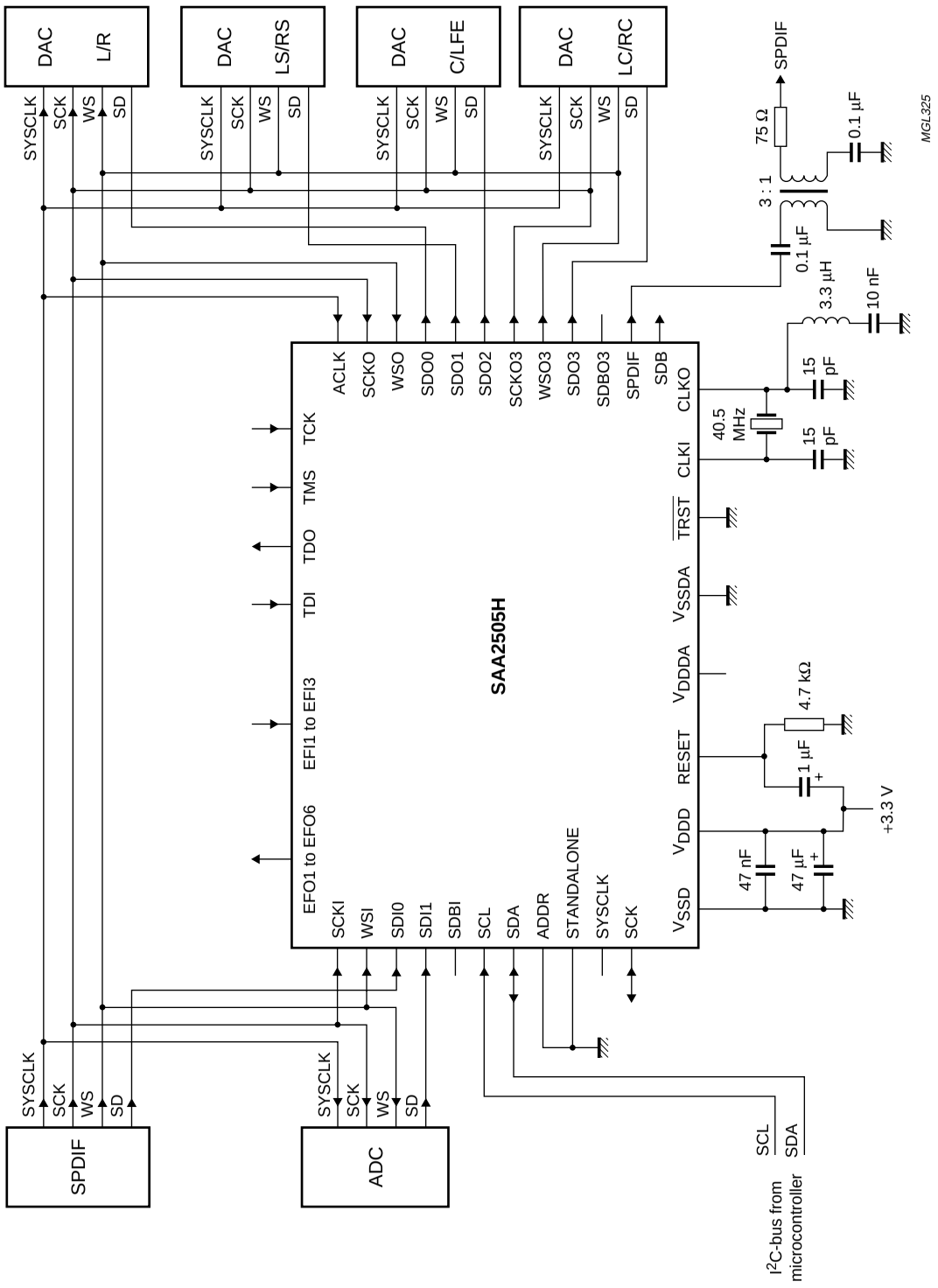
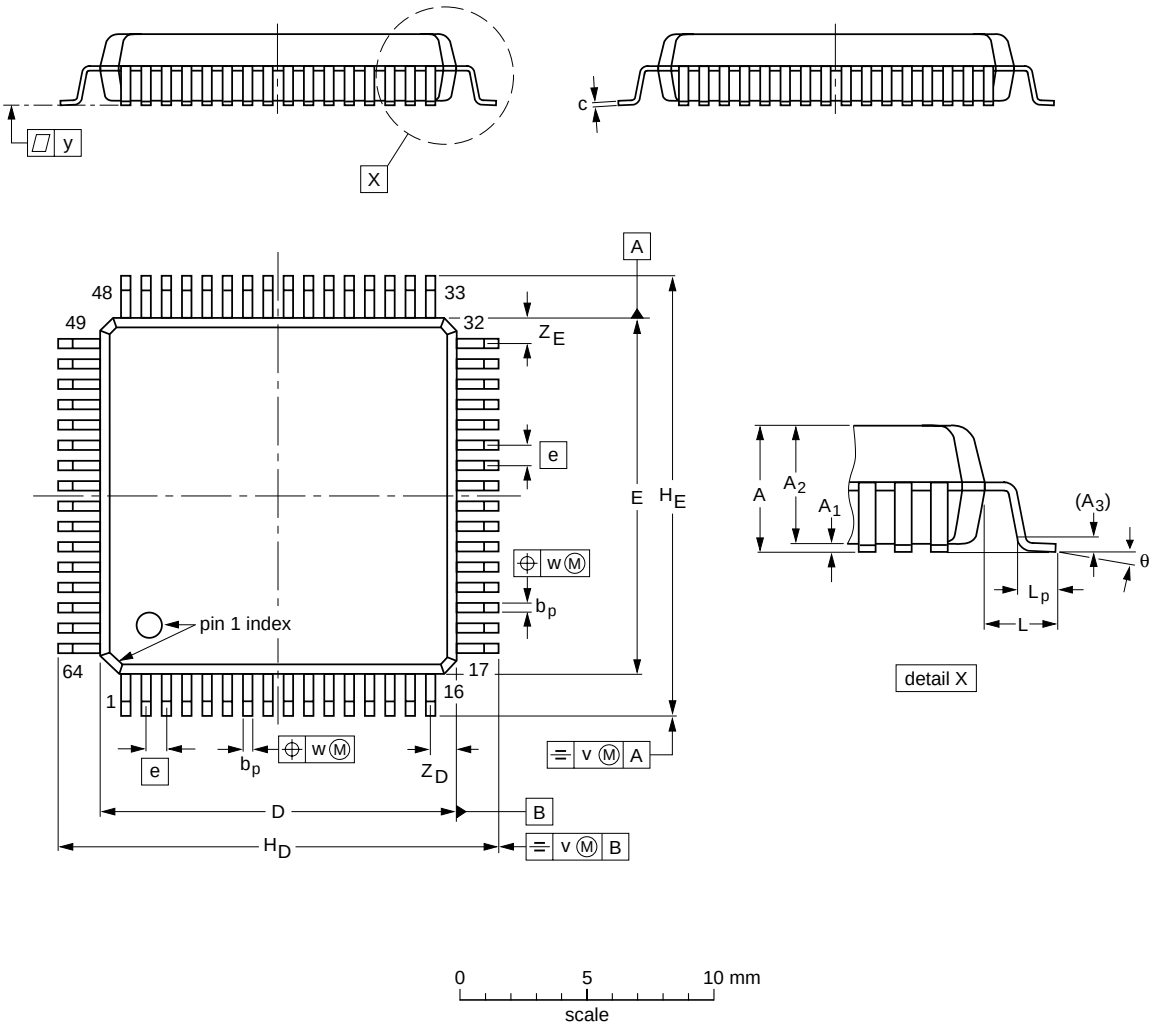


Fig.11 Application diagram for SAA2505H.

PACKAGE OUTLINE

QFP64: plastic quad flat package; 64 leads (lead length 1.6 mm); body 14 x 14 x 2.7 mm **SOT393-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_D	H_E	L	L_p	v	w	y	$Z_D^{(1)}$	$Z_E^{(1)}$	θ
mm	3.00	0.25 0.10	2.75 2.55	0.25	0.45 0.30	0.23 0.13	14.1 13.9	14.1 13.9	0.8	17.45 16.95	17.45 16.95	1.60	1.03 0.73	0.16	0.16	0.10	1.2 0.8	1.2 0.8	7^o 0^o

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT393-1		MS-022				~~96-05-21~~ 97-08-04

SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"IC Package Databook"* (order code 9398 652 90011).

Reflow soldering

Reflow soldering techniques are suitable for all QFP packages.

The choice of heating method may be influenced by larger plastic QFP packages (44 leads, or more). If infrared or vapour phase heating is used and the large packages are not absolutely dry (less than 0.1% moisture content by weight), vaporization of the small amount of moisture in them can cause cracking of the plastic body. For more information, refer to the Drypack chapter in our *"Quality Reference Handbook"* (order code 9397 750 00192).

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several methods exist for reflowing; for example, infrared/convection heating in a conveyor type oven. Throughput times (preheating, soldering and cooling) vary between 50 and 300 seconds depending on heating method. Typical reflow peak temperatures range from 215 to 250 °C.

Wave soldering

Wave soldering is **not** recommended for QFP packages. This is because of the likelihood of solder bridging due to closely-spaced leads and the possibility of incomplete solder penetration in multi-lead devices.

CAUTION
Wave soldering is NOT applicable for all QFP packages with a pitch (e) equal or less than 0.5 mm.

If wave soldering cannot be avoided, for QFP packages with a pitch (e) larger than 0.5 mm, the following conditions must be observed:

- **A double-wave (a turbulent wave with high upward pressure followed by a smooth laminar wave) soldering technique should be used.**
- **The footprint must be at an angle of 45° to the board direction and must incorporate solder thieves downstream and at the side corners.**

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder is 10 seconds, if cooled to less than 150 °C within 6 seconds. Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

Repairing soldered joints

Fix the component by first soldering two diagonally-opposite end leads. Use only a low voltage soldering iron (less than 24 V) applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C. When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

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